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### Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

### Applications of Embedded - FPGAs

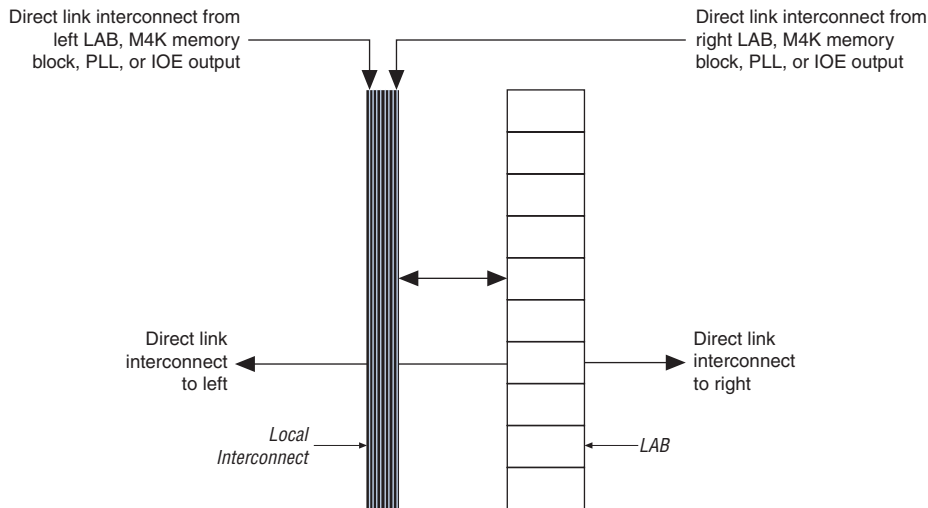
The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

#### Details

Product Status	Obsolete
Number of LABs/CLBs	598
Number of Logic Elements/Cells	5980
Total RAM Bits	92160
Number of I/O	98
Number of Gates	-
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	144-LQFP
Supplier Device Package	144-TQFP (20x20)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/intel/ep1c6t144c7n">https://www.e-xfl.com/product-detail/intel/ep1c6t144c7n</a>

performance and flexibility. Each LE can drive 30 other LEs through fast local and direct link interconnects. Figure 2–3 shows the direct link connection.

**Figure 2–3. Direct Link Connection**



## LAB Control Signals

Each LAB contains dedicated logic for driving control signals to its LEs. The control signals include two clocks, two clock enables, two asynchronous clears, synchronous clear, asynchronous preset/load, synchronous load, and add/subtract control signals. This gives a maximum of 10 control signals at a time. Although synchronous load and clear signals are generally used when implementing counters, they can also be used with other functions.

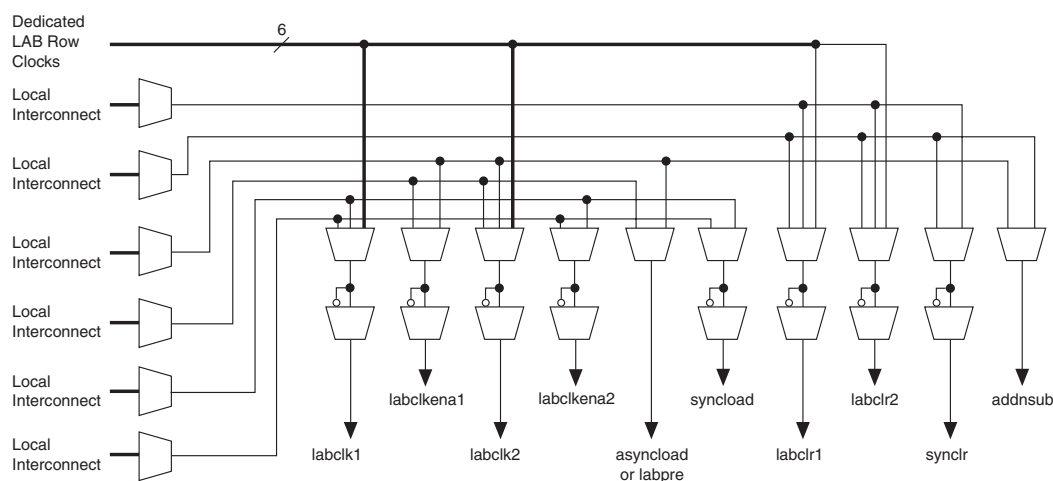
Each LAB can use two clocks and two clock enable signals. Each LAB's clock and clock enable signals are linked. For example, any LE in a particular LAB using the `labclk1` signal will also use `labckena1`. If the LAB uses both the rising and falling edges of a clock, it also uses both LAB-wide clock signals. Deasserting the clock enable signal will turn off the LAB-wide clock.

Each LAB can use two asynchronous clear signals and an asynchronous load/preset signal. The asynchronous load acts as a preset when the asynchronous load data input is tied high.

With the LAB-wide `addnsub` control signal, a single LE can implement a one-bit adder and subtractor. This saves LE resources and improves performance for logic functions such as DSP correlators and signed multipliers that alternate between addition and subtraction depending on data.

The LAB row clocks [5 : 0] and LAB local interconnect generate the LAB-wide control signals. The MultiTrack™ interconnect's inherent low skew allows clock and control signal distribution in addition to data. [Figure 2-4](#) shows the LAB control signal generation circuit.

**Figure 2-4. LAB-Wide Control Signals**



## Logic Elements

The smallest unit of logic in the Cyclone architecture, the LE, is compact and provides advanced features with efficient logic utilization. Each LE contains a four-input LUT, which is a function generator that can implement any function of four variables. In addition, each LE contains a programmable register and carry chain with carry select capability. A single LE also supports dynamic single bit addition or subtraction mode selectable by a LAB-wide control signal. Each LE drives all types of interconnects: local, row, column, LUT chain, register chain, and direct link interconnects. See [Figure 2-5](#).

### *Dynamic Arithmetic Mode*

The dynamic arithmetic mode is ideal for implementing adders, counters, accumulators, wide parity functions, and comparators. An LE in dynamic arithmetic mode uses four 2-input LUTs configurable as a dynamic adder/subtractor. The first two 2-input LUTs compute two summations based on a possible carry-in of 1 or 0; the other two LUTs generate carry outputs for the two chains of the carry select circuitry. As shown in [Figure 2-7](#), the LAB carry-in signal selects either the `carry-in0` or `carry-in1` chain. The selected chain's logic level in turn determines which parallel sum is generated as a combinatorial or registered output. For example, when implementing an adder, the sum output is the selection of two possible calculated sums:

$$\text{data1} + \text{data2} + \text{carry-in0}$$

or

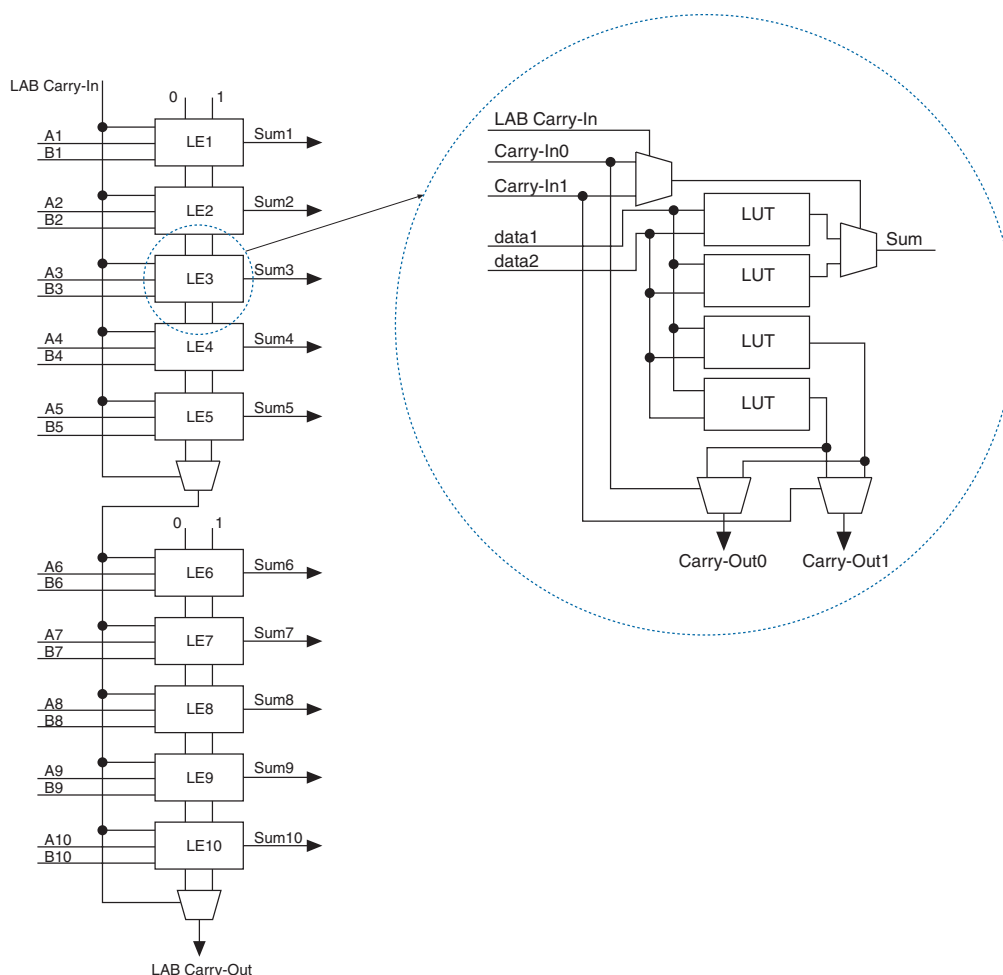
$$\text{data1} + \text{data2} + \text{carry-in1}$$

The other two LUTs use the `data1` and `data2` signals to generate two possible carry-out signals—one for a carry of 1 and the other for a carry of 0. The `carry-in0` signal acts as the carry select for the `carry-out0` output and `carry-in1` acts as the carry select for the `carry-out1` output. LEs in arithmetic mode can drive out registered and unregistered versions of the LUT output.

The dynamic arithmetic mode also offers clock enable, counter enable, synchronous up/down control, synchronous clear, synchronous load, and dynamic adder/subtractor options. The LAB local interconnect data inputs generate the counter enable and synchronous up/down control signals. The synchronous clear and synchronous load options are LAB-wide signals that affect all registers in the LAB. The Quartus II software automatically places any registers that are not used by the counter into other LABs. The `addnsub` LAB-wide signal controls whether the LE acts as an adder or subtractor.

Figure 2–8 shows the carry-select circuitry in a LAB for a 10-bit full adder. One portion of the LUT generates the sum of two bits using the input signals and the appropriate carry-in bit; the sum is routed to the output of the LE. The register can be bypassed for simple adders or used for accumulator functions. Another portion of the LUT generates carry-out bits. A LAB-wide carry-in bit selects which chain is used for the addition of given inputs. The carry-in signal for each chain, *carry-in0* or *carry-in1*, selects the carry-out to carry forward to the carry-in signal of the next-higher-order bit. The final carry-out signal is routed to an LE, where it is fed to local, row, or column interconnects.

**Figure 2–8. Carry Select Chain**



The Quartus II Compiler automatically creates carry chain logic during design processing, or you can create it manually during design entry. Parameterized functions such as LPM functions automatically take advantage of carry chains for the appropriate functions.

The Quartus II Compiler creates carry chains longer than 10 LEs by linking LABs together automatically. For enhanced fitting, a long carry chain runs vertically allowing fast horizontal connections to M4K memory blocks. A carry chain can continue as far as a full column.

### *Clear and Preset Logic Control*

LAB-wide signals control the logic for the register's clear and preset signals. The LE directly supports an asynchronous clear and preset function. The register preset is achieved through the asynchronous load of a logic high. The direct asynchronous preset does not require a NOT-gate push-back technique. Cyclone devices support simultaneous preset/ asynchronous load and clear signals. An asynchronous clear signal takes precedence if both signals are asserted simultaneously. Each LAB supports up to two clears and one preset signal.

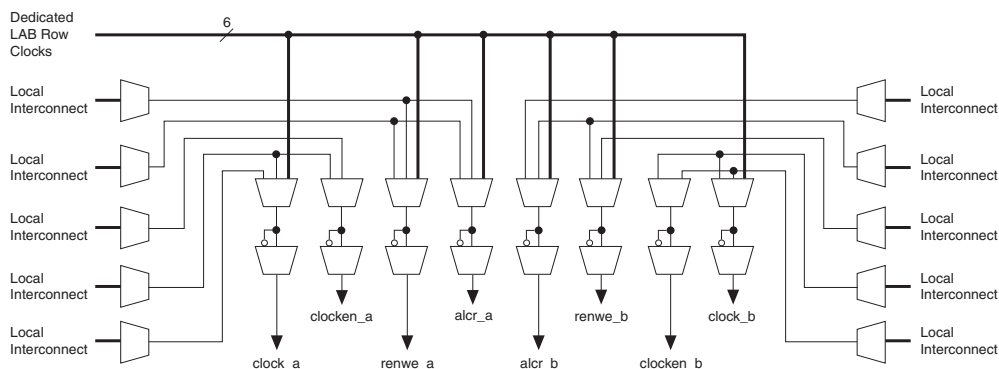
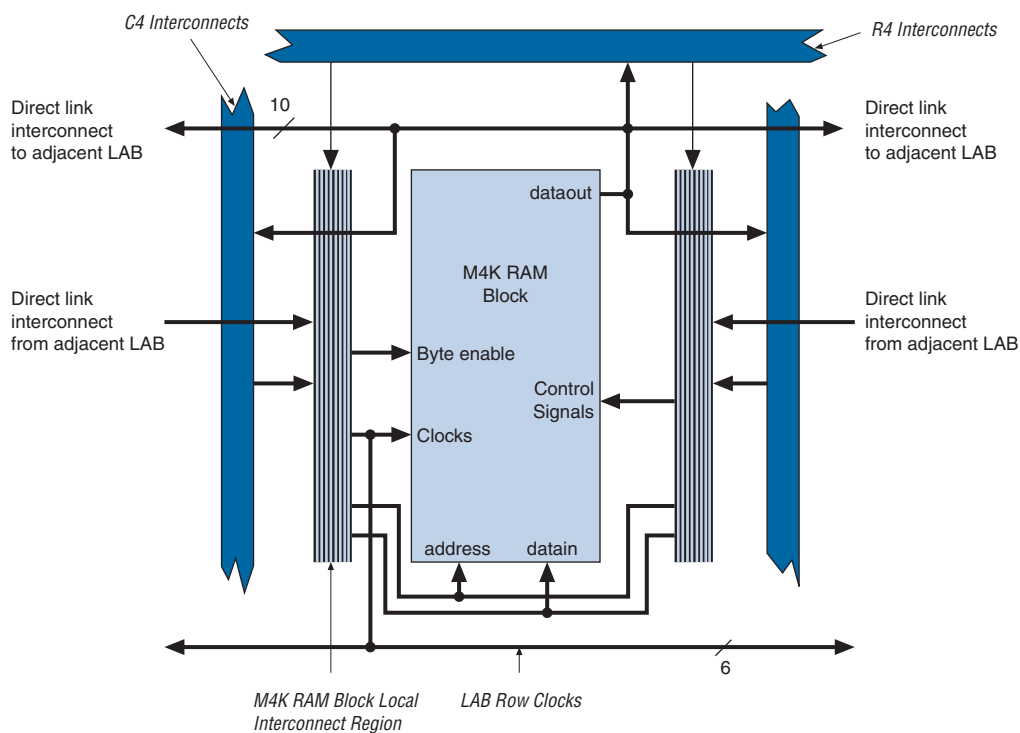
In addition to the clear and preset ports, Cyclone devices provide a chip-wide reset pin (DEV\_CLRn) that resets all registers in the device. An option set before compilation in the Quartus II software controls this pin. This chip-wide reset overrides all other control signals.

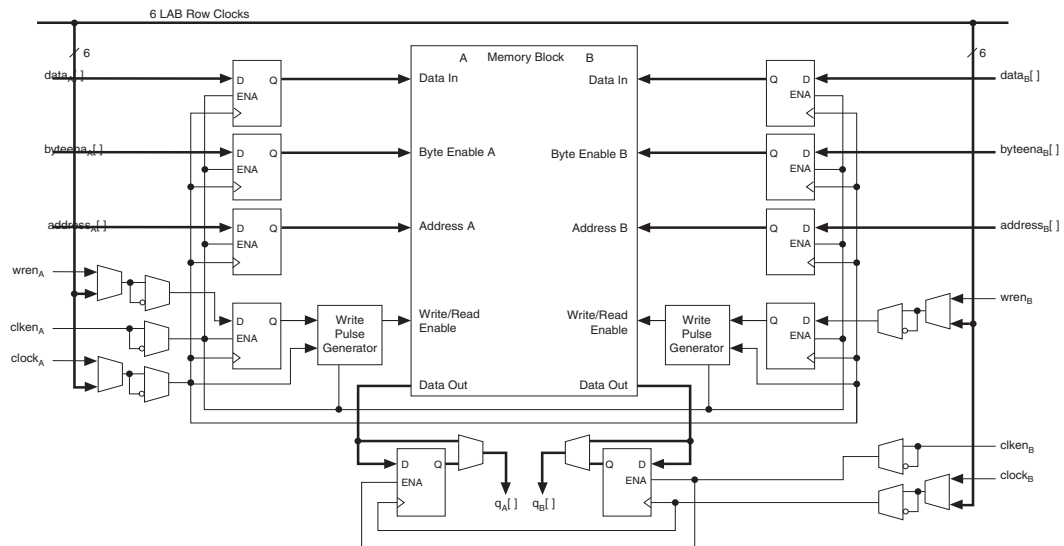
## **MultiTrack Interconnect**

In the Cyclone architecture, connections between LEs, M4K memory blocks, and device I/O pins are provided by the MultiTrack interconnect structure with DirectDrive™ technology. The MultiTrack interconnect consists of continuous, performance-optimized routing lines of different speeds used for inter- and intra-design block connectivity. The Quartus II Compiler automatically places critical design paths on faster interconnects to improve design performance.

DirectDrive technology is a deterministic routing technology that ensures identical routing resource usage for any function regardless of placement within the device. The MultiTrack interconnect and DirectDrive technology simplify the integration stage of block-based designing by eliminating the re-optimization cycles that typically follow design changes and additions.

The MultiTrack interconnect consists of row and column interconnects that span fixed distances. A routing structure with fixed length resources for all devices allows predictable and repeatable performance when

**Figure 2–15. M4K RAM Block Control Signals****Figure 2–16. M4K RAM Block LAB Row Interface**

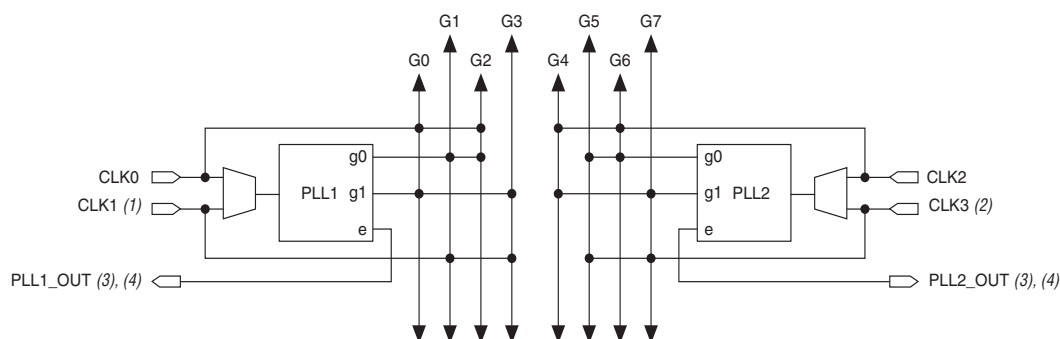
**Figure 2–18. Input/Output Clock Mode in True Dual-Port Mode** *Notes (1), (2)***Notes to Figure 2–18:**

- (1) All registers shown have asynchronous clear ports.
- (2) Violating the setup or hold time on the address registers could corrupt the memory contents. This applies to both read and write operations.



Figure 2–26 shows the PLL global clock connections.

**Figure 2–26. Cyclone PLL Global Clock Connections**



**Notes to Figure 2–26:**

- (1) PLL 1 supports one single-ended or LVDS input via pins CLK0 and CLK1.
- (2) PLL2 supports one single-ended or LVDS input via pins CLK2 and CLK3.
- (3) PLL1\_OUT and PLL2\_OUT support single-ended or LVDS output. If external output is not required, these pins are available as regular user I/O pins.
- (4) The EP1C3 device in the 100-pin TQFP package does not support external clock output. The EP1C6 device in the 144-pin TQFP package does not support external clock output from PLL2.

Table 2–7 shows the global clock network sources available in Cyclone devices.

**Table 2–7. Global Clock Network Sources (Part 1 of 2)**

Source		GCLK0	GCLK1	GCLK2	GCLK3	GCLK4	GCLK5	GCLK6	GCLK7
PLL Counter Output	PLL1 G0	—	✓	✓	—	—	—	—	—
	PLL1 G1	✓	—	—	✓	—	—	—	—
	PLL2 G0 (1)	—	—	—	—	—	✓	✓	—
	PLL2 G1 (1)	—	—	—	—	✓	—	—	✓
Dedicated Clock Input Pins	CLK0	✓	—	✓	—	—	—	—	—
	CLK1 (2)	—	✓	—	✓	—	—	—	—
	CLK2	—	—	—	—	✓	—	✓	—
	CLK3 (2)	—	—	—	—	—	✓	—	✓

**Table 2–7. Global Clock Network Sources (Part 2 of 2)**

Source		GCLK0	GCLK1	GCLK2	GCLK3	GCLK4	GCLK5	GCLK6	GCLK7
Dual-Purpose Clock Pins	DPCLK0 (3)	—	—	—	✓	—	—	—	—
	DPCLK1 (3)	—	—	✓	—	—	—	—	—
	DPCLK2	✓	—	—	—	—	—	—	—
	DPCLK3	—	—	—	—	✓	—	—	—
	DPCLK4	—	—	—	—	—	—	✓	—
	DPCLK5 (3)	—	—	—	—	—	—	—	✓
	DPCLK6	—	—	—	—	—	✓	—	—
	DPCLK7	—	✓	—	—	—	—	—	—

**Notes to Table 2–7:**

- (1) EP1C3 devices only have one PLL (PLL 1).
- (2) EP1C3 devices in the 100-pin TQFP package do not have dedicated clock pins CLK1 and CLK3.
- (3) EP1C3 devices in the 100-pin TQFP package do not have the DPCLK0, DPCLK1, or DPCLK5 pins.

## Clock Multiplication and Division

Cyclone PLLs provide clock synthesis for PLL output ports using  $m/(n \times \text{post scale counter})$  scaling factors. The input clock is divided by a pre-scale divider,  $n$ , and is then multiplied by the  $m$  feedback factor. The control loop drives the VCO to match  $f_{IN} \times (m/n)$ . Each output port has a unique post-scale counter to divide down the high-frequency VCO. For multiple PLL outputs with different frequencies, the VCO is set to the least-common multiple of the output frequencies that meets its frequency specifications. Then, the post-scale dividers scale down the output frequency for each output port. For example, if the output frequencies required from one PLL are 33 and 66 MHz, the VCO is set to 330 MHz (the least-common multiple in the VCO's range).

Each PLL has one pre-scale divider,  $n$ , that can range in value from 1 to 32. Each PLL also has one multiply divider,  $m$ , that can range in value from 2 to 32. Global clock outputs have two post scale G dividers for global clock outputs, and external clock outputs have an E divider for external clock output, both ranging from 1 to 32. The Quartus II software automatically chooses the appropriate scaling factors according to the input frequency, multiplication, and division values entered.

## External Clock Inputs

Each PLL supports single-ended or differential inputs for source-synchronous receivers or for general-purpose use. The dedicated clock pins (CLK[3..0]) feed the PLL inputs. These dual-purpose pins can also act as LVDS input pins. See [Figure 2-25](#).

[Table 2-8](#) shows the I/O standards supported by PLL input and output pins.

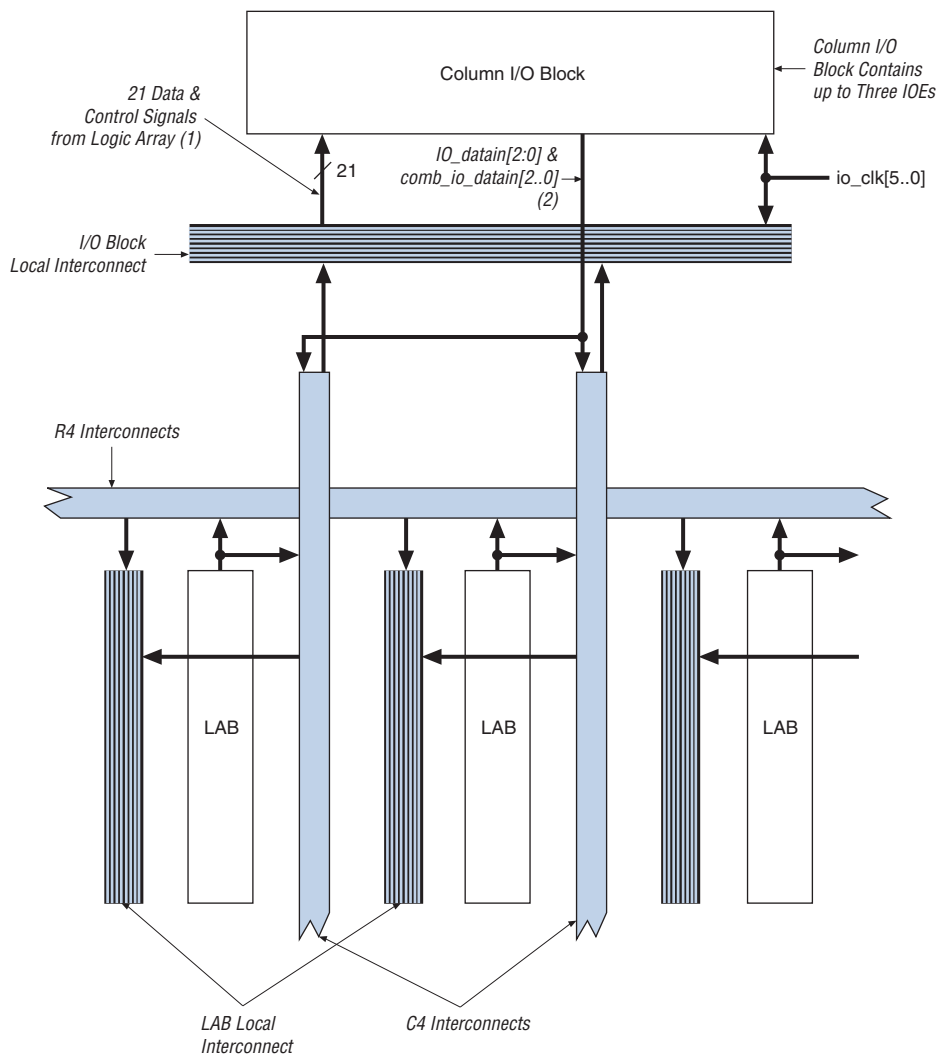
<b>Table 2-8. PLL I/O Standards</b>		
<b>I/O Standard</b>	<b>CLK Input</b>	<b>EXTCLK Output</b>
3.3-V LVTTTL/LVCMOS	✓	✓
2.5-V LVTTTL/LVCMOS	✓	✓
1.8-V LVTTTL/LVCMOS	✓	✓
1.5-V LVCMOS	✓	✓
3.3-V PCI	✓	✓
LVDS	✓	✓
SSTL-2 class I	✓	✓
SSTL-2 class II	✓	✓
SSTL-3 class I	✓	✓
SSTL-3 class II	✓	✓
Differential SSTL-2	—	✓

For more information on LVDS I/O support, refer to “[LVDS I/O Pins](#)” on [page 2-54](#).

## External Clock Outputs

Each PLL supports one differential or one single-ended output for source-synchronous transmitters or for general-purpose external clocks. If the PLL does not use these PLL\_OUT pins, the pins are available for use as general-purpose I/O pins. The PLL\_OUT pins support all I/O standards shown in [Table 2-8](#).

The external clock outputs do not have their own V<sub>CC</sub> and ground voltage supplies. Therefore, to minimize jitter, do not place switching I/O pins next to these output pins. The EP1C3 device in the 100-pin TQFP package

**Figure 2–29. Column I/O Block Connection to the Interconnect****Notes to Figure 2–29:**

- (1) The 21 data and control signals consist of three data out lines, `io_dataout[2..0]`, three output enables, `io_coe[2..0]`, three input clock enables, `io_cce_in[2..0]`, three output clock enables, `io_cce_out[2..0]`, three clocks, `io_cclk[2..0]`, three asynchronous clear signals, `io_caclr[2..0]`, and three synchronous clear signals, `io_csclr[2..0]`.
- (2) Each of the three IOEs in the column I/O block can have one `io_datain` input (combinatorial or registered) and one `comb_io_datain` (combinatorial) input.

to automatically minimize setup time while providing a zero hold time. Programmable delays can increase the register-to-pin delays for output registers. Table 2–9 shows the programmable delays for Cyclone devices.

<b>Table 2–9. Cyclone Programmable Delay Chain</b>	
<b>Programmable Delays</b>	<b>Quartus II Logic Option</b>
Input pin to logic array delay	Decrease input delay to internal cells
Input pin to input register delay	Decrease input delay to input registers
Output pin delay	Increase delay to output pin

There are two paths in the IOE for a combinatorial input to reach the logic array. Each of the two paths can have a different delay. This allows you adjust delays from the pin to internal LE registers that reside in two different areas of the device. The designer sets the two combinatorial input delays by selecting different delays for two different paths under the **Decrease input delay to internal cells** logic option in the Quartus II software. When the input signal requires two different delays for the combinatorial input, the input register in the IOE is no longer available.

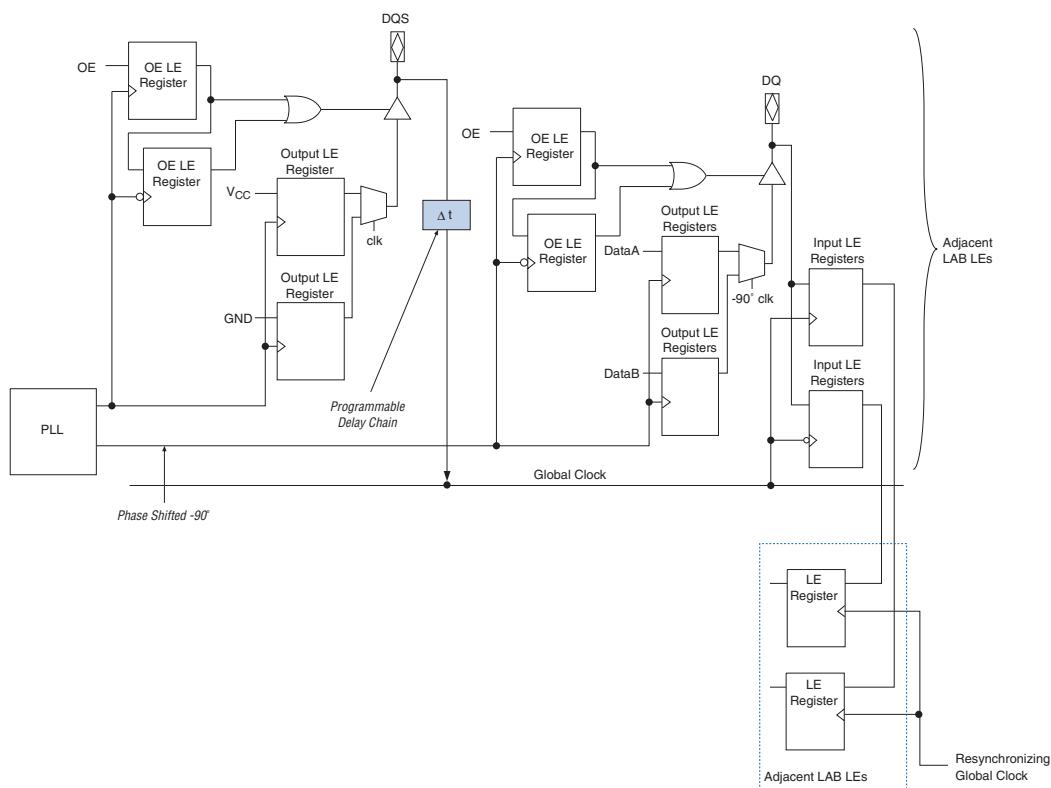
The IOE registers in Cyclone devices share the same source for clear or preset. The designer can program preset or clear for each individual IOE. The designer can also program the registers to power up high or low after configuration is complete. If programmed to power up low, an asynchronous clear can control the registers. If programmed to power up high, an asynchronous preset can control the registers. This feature prevents the inadvertent activation of another device's active-low input upon power up. If one register in an IOE uses a preset or clear signal then all registers in the IOE must use that same signal if they require preset or clear. Additionally a synchronous reset signal is available to the designer for the IOE registers.

## External RAM Interfacing

Cyclone devices support DDR SDRAM and FCRAM interfaces at up to 133 MHz through dedicated circuitry.

## DDR SDRAM and FCRAM

Cyclone devices have dedicated circuitry for interfacing with DDR SDRAM. All I/O banks support DDR SDRAM and FCRAM I/O pins. However, the configuration input pins in bank 1 must operate at 2.5 V because the SSTL-2  $V_{CCIO}$  level is 2.5 V. Additionally, the configuration

**Figure 2–34. DDR SDRAM and FCRAM Interfacing**

## Programmable Drive Strength

The output buffer for each Cyclone device I/O pin has a programmable drive strength control for certain I/O standards. The LVTTTL and LVCMOS standards have several levels of drive strength that the designer can control. SSTL-3 class I and II, and SSTL-2 class I and II support a minimum setting, the lowest drive strength that guarantees the  $I_{OH}/I_{OL}$

**Table 4–16. Cyclone Device Capacitance** *Note (14)*

Symbol	Parameter	Typical	Unit
$C_{IO}$	Input capacitance for user I/O pin	4.0	pF
$C_{LVDS}$	Input capacitance for dual-purpose LVDS/user I/O pin	4.7	pF
$C_{VREF}$	Input capacitance for dual-purpose $V_{REF}$ /user I/O pin.	12.0	pF
$C_{DPCLK}$	Input capacitance for dual-purpose $DPCLK$ /user I/O pin.	4.4	pF
$C_{CLK}$	Input capacitance for CLK pin.	4.7	pF

**Notes to Tables 4–1 through 4–16:**

- (1) Refer to the *Operating Requirements for Altera Devices Data Sheet*.
- (2) Conditions beyond those listed in Table 4–1 may cause permanent damage to a device. Additionally, device operation at the absolute maximum ratings for extended periods of time may have adverse affects on the device.
- (3) Minimum DC input is –0.5 V. During transitions, the inputs may undershoot to –2.0 V or overshoot to 4.6 V for input currents less than 100 mA and periods shorter than 20 ns.
- (4) Maximum  $V_{CC}$  rise time is 100 ms, and  $V_{CC}$  must rise monotonically.
- (5) All pins, including dedicated inputs, clock, I/O, and JTAG pins, may be driven before  $V_{CCINT}$  and  $V_{CCIO}$  are powered.
- (6) Typical values are for  $T_A = 25^\circ\text{C}$ ,  $V_{CCINT} = 1.5\text{ V}$ , and  $V_{CCIO} = 1.5\text{ V}$ , 1.8 V, 2.5 V, and 3.3 V.
- (7)  $V_I = \text{ground}$ , no load, no toggling inputs.
- (8) This value is specified for normal device operation. The value may vary during power-up. This applies for all  $V_{CCIO}$  settings (3.3, 2.5, 1.8, and 1.5 V).
- (9)  $R_{CONF}$  is the measured value of internal pull-up resistance when the I/O pin is tied directly to GND.  $R_{CONF}$  value will be lower if an external source drives the pin higher than  $V_{CCIO}$ .
- (10) Pin pull-up resistance values will lower if an external source drives the pin higher than  $V_{CCIO}$ .
- (11) Drive strength is programmable according to values in *Cyclone Architecture* chapter in the *Cyclone Device Handbook*.
- (12) Overdrive is possible when a 1.5 V or 1.8 V and a 2.5 V or 3.3 V input signal feeds an input pin. Turn on “Allow voltage overdrive” for LVTTTL/LVCMOS input pins in the Assignments > Device > Device and Pin Options > Pin Placement tab when a device has this I/O combination. However, higher leakage current is expected.
- (13) The Cyclone LVDS interface requires a resistor network outside of the transmitter channels.
- (14) Capacitance is sample-tested only. Capacitance is measured using time-domain reflections (TDR). Measurement accuracy is within  $\pm 0.5\text{ pF}$ .

**Table 4–22. IOE Internal Timing Microparameter Descriptions**

Symbol	Parameter
$t_{SU}$	IOE input and output register setup time before clock
$t_H$	IOE input and output register hold time after clock
$t_{CO}$	IOE input and output register clock-to-output delay
$t_{PIN2COMBOUT\_R}$	Row input pin to IOE combinatorial output
$t_{PIN2COMBOUT\_C}$	Column input pin to IOE combinatorial output
$t_{COMBIN2PIN\_R}$	Row IOE data input to combinatorial output pin
$t_{COMBIN2PIN\_C}$	Column IOE data input to combinatorial output pin
$t_{CLR}$	Minimum clear pulse width
$t_{PRE}$	Minimum preset pulse width
$t_{CLKHL}$	Minimum clock high or low time

**Table 4–23. M4K Block Internal Timing Microparameter Descriptions**

Symbol	Parameter
$t_{M4KRC}$	Synchronous read cycle time
$t_{M4KWC}$	Synchronous write cycle time
$t_{M4KWERESU}$	Write or read enable setup time before clock
$t_{M4KWEREH}$	Write or read enable hold time after clock
$t_{M4KBESU}$	Byte enable setup time before clock
$t_{M4KBEH}$	Byte enable hold time after clock
$t_{M4KDATAASU}$	A port data setup time before clock
$t_{M4KDATAAH}$	A port data hold time after clock
$t_{M4KADDRASU}$	A port address setup time before clock
$t_{M4KADDRAH}$	A port address hold time after clock
$t_{M4KDATABSU}$	B port data setup time before clock
$t_{M4KDATABH}$	B port data hold time after clock
$t_{M4KADDRBSU}$	B port address setup time before clock
$t_{M4KADDRBH}$	B port address hold time after clock
$t_{M4KDATAO1}$	Clock-to-output delay when using output registers
$t_{M4KDATAO2}$	Clock-to-output delay without output registers
$t_{M4KCLKHL}$	Minimum clock high or low time
$t_{M4KCLR}$	Minimum clear pulse width



**Table 4–27. M4K Block Internal Timing Microparameters**

Symbol	-6		-7		-8		Unit
	Min	Max	Min	Max	Min	Max	
$t_{M4KRC}$	—	4,379		5,035		5,691	ps
$t_{M4KWC}$	—	2,910		3,346		3,783	ps
$t_{M4KWRESU}$	72	—	82	—	93	—	ps
$t_{M4KWEREH}$	43	—	49	—	55	—	ps
$t_{M4KBESU}$	72	—	82	—	93	—	ps
$t_{M4KBEH}$	43	—	49	—	55	—	ps
$t_{M4KDATAASU}$	72	—	82	—	93	—	ps
$t_{M4KDATAAH}$	43	—	49	—	55	—	ps
$t_{M4KADDRASU}$	72	—	82	—	93	—	ps
$t_{M4KADDRAH}$	43	—	49	—	55	—	ps
$t_{M4KDATABSU}$	72	—	82	—	93	—	ps
$t_{M4KDATA BH}$	43	—	49	—	55	—	ps
$t_{M4KADDRBSU}$	72	—	82	—	93	—	ps
$t_{M4KADDRBH}$	43	—	49	—	55	—	ps
$t_{M4KDATA CO1}$	—	621	—	714	—	807	ps
$t_{M4KDATA CO2}$	—	4,351	—	5,003	—	5,656	ps
$t_{M4KCLKHL}$	1,234	—	1,562	—	1,818	—	ps
$t_{M4KCLR}$	286	—	328	—	371	—	ps

**Table 4–28. Routing Delay Internal Timing Microparameters**

Symbol	-6		-7		-8		Unit
	Min	Max	Min	Max	Min	Max	
$t_{R4}$	—	261	—	300	—	339	ps
$t_{C4}$	—	338	—	388	—	439	ps
$t_{LOCAL}$	—	244	—	281	—	318	ps

## External Timing Parameters

External timing parameters are specified by device density and speed grade. [Figure 4–2](#) shows the timing model for bidirectional IOE pin timing. All registers are within the IOE.

**Table 4–42. Cyclone I/O Standard Output Delay Adders for Fast Slew Rate on Column Pins (Part 2 of 2)**

Standard		-6 Speed Grade		-7 Speed Grade		-8 Speed Grade		Unit
		Min	Max	Min	Max	Min	Max	
2.5-V LVTTTL	2 mA	—	329	—	378	—	427	ps
	8 mA	—	–661	—	–761	—	–860	ps
	12 mA	—	–655	—	–754	—	–852	ps
	16 mA	—	–795	—	–915	—	–1034	ps
1.8-V LVTTTL	2 mA	—	4	—	4	—	5	ps
	8 mA	—	–208	—	–240	—	–271	ps
	12 mA	—	–208	—	–240	—	–271	ps
1.5-V LVTTTL	2 mA	—	2,288	—	2,631	—	2,974	ps
	4 mA	—	608	—	699	—	790	ps
	8 mA	—	292	—	335	—	379	ps
SSTL-3 class I		—	–410	—	–472	—	–533	ps
SSTL-3 class II		—	–811	—	–933	—	–1,055	ps
SSTL-2 class I		—	–485	—	–558	—	–631	ps
SSTL-2 class II		—	–758	—	–872	—	–986	ps
LVDS		—	–998	—	–1,148	—	–1,298	ps

**Table 4–43. Cyclone I/O Standard Output Delay Adders for Fast Slew Rate on Row Pins (Part 1 of 2)**

Standard		-6 Speed Grade		-7 Speed Grade		-8 Speed Grade		Unit
		Min	Max	Min	Max	Min	Max	
LVCMOS	2 mA	—	0	—	0	—	0	ps
	4 mA	—	–489	—	–563	—	–636	ps
	8 mA	—	–855	—	–984	—	–1,112	ps
	12 mA	—	–993	—	–1,142	—	–1,291	ps
3.3-V LVTTTL	4 mA	—	0	—	0	—	0	ps
	8 mA	—	–347	—	–400	—	–452	ps
	12 mA	—	–858	—	–987	—	–1,116	ps
	16 mA	—	–819	—	–942	—	–1,065	ps
	24 mA	—	–993	—	–1,142	—	–1,291	ps
2.5-V LVTTTL	2 mA	—	329	—	378	—	427	ps
	8 mA	—	–661	—	–761	—	–860	ps
	12 mA	—	–655	—	–754	—	–852	ps
	16 mA	—	–795	—	–915	—	–1,034	ps

**Table 4–43. Cyclone I/O Standard Output Delay Adders for Fast Slew Rate on Row Pins (Part 2 of 2)**

Standard		-6 Speed Grade		-7 Speed Grade		-8 Speed Grade		Unit
		Min	Max	Min	Max	Min	Max	
1.8-V LVTTTL	2 mA	—	1,290	—	1,483	—	1,677	ps
	8 mA	—	4	—	4	—	5	ps
	12 mA	—	–208	—	–240	—	–271	ps
1.5-V LVTTTL	2 mA	—	2,288	—	2,631	—	2,974	ps
	4 mA	—	608	—	699	—	790	ps
	8 mA	—	292	—	335	—	379	ps
3.3-V PCI (1)		—	–877	—	–1,009	—	–1,141	ps
SSTL-3 class I		—	–410	—	–472	—	–533	ps
SSTL-3 class II		—	–811	—	–933	—	–1,055	ps
SSTL-2 class I		—	–485	—	–558	—	–631	ps
SSTL-2 class II		—	–758	—	–872	—	–986	ps
LVDS		—	–998	—	–1,148	—	–1,298	ps

**Table 4–44. Cyclone I/O Standard Output Delay Adders for Slow Slew Rate on Column Pins (Part 1 of 2)**

I/O Standard		-6 Speed Grade		-7 Speed Grade		-8 Speed Grade		Unit
		Min	Max	Min	Max	Min	Max	
LVCMOS	2 mA	—	1,800	—	2,070	—	2,340	ps
	4 mA	—	1,311	—	1,507	—	1,704	ps
	8 mA	—	945	—	1,086	—	1,228	ps
	12 mA	—	807	—	928	—	1,049	ps
3.3-V LVTTTL	4 mA	—	1,831	—	2,105	—	2,380	ps
	8 mA	—	1,484	—	1,705	—	1,928	ps
	12 mA	—	973	—	1,118	—	1,264	ps
	16 mA	—	1,012	—	1,163	—	1,315	ps
	24 mA	—	838	—	963	—	1,089	ps
2.5-V LVTTTL	2 mA	—	2,747	—	3,158	—	3,570	ps
	8 mA	—	1,757	—	2,019	—	2,283	ps
	12 mA	—	1,763	—	2,026	—	2,291	ps
	16 mA	—	1,623	—	1,865	—	2,109	ps
1.8-V LVTTTL	2 mA	—	5,506	—	6,331	—	7,157	ps
	8 mA	—	4,220	—	4,852	—	5,485	ps
	12 mA	—	4,008	—	4,608	—	5,209	ps

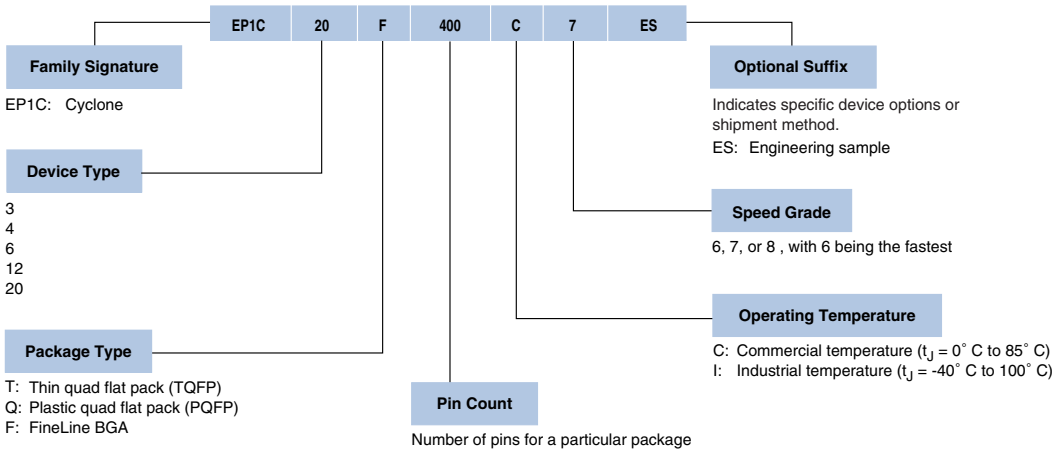
**Table 4–44. Cyclone I/O Standard Output Delay Adders for Slow Slew Rate on Column Pins (Part 2 of 2)**

I/O Standard		-6 Speed Grade		-7 Speed Grade		-8 Speed Grade		Unit
		Min	Max	Min	Max	Min	Max	
1.5-V LVTTTL	2 mA	—	6,789	—	7,807	—	8,825	ps
	4 mA	—	5,109	—	5,875	—	6,641	ps
	8 mA	—	4,793	—	5,511	—	6,230	ps
SSTL-3 class I		—	1,390	—	1,598	—	1,807	ps
SSTL-3 class II		—	989	—	1,137	—	1,285	ps
SSTL-2 class I		—	1,965	—	2,259	—	2,554	ps
SSTL-2 class II		—	1,692	—	1,945	—	2,199	ps
LVDS		—	802	—	922	—	1,042	ps

**Table 4–45. Cyclone I/O Standard Output Delay Adders for Slow Slew Rate on Row Pins (Part 1 of 2)**

I/O Standard		-6 Speed Grade		-7 Speed Grade		-8 Speed Grade		Unit
		Min	Max	Min	Max	Min	Max	
LVCMOS	2 mA	—	1,800	—	2,070	—	2,340	ps
	4 mA	—	1,311	—	1,507	—	1,704	ps
	8 mA	—	945	—	1,086	—	1,228	ps
	12 mA	—	807	—	928	—	1,049	ps
3.3-V LVTTTL	4 mA	—	1,831	—	2,105	—	2,380	ps
	8 mA	—	1,484	—	1,705	—	1,928	ps
	12 mA	—	973	—	1,118	—	1,264	ps
	16 mA	—	1,012	—	1,163	—	1,315	ps
	24 mA	—	838	—	963	—	1,089	ps
2.5-V LVTTTL	2 mA	—	2,747	—	3,158	—	3,570	ps
	8 mA	—	1,757	—	2,019	—	2,283	ps
	12 mA	—	1,763	—	2,026	—	2,291	ps
	16 mA	—	1,623	—	1,865	—	2,109	ps
1.8-V LVTTTL	2 mA	—	5,506	—	6,331	—	7,157	ps
	8 mA	—	4,220	—	4,852	—	5,485	ps
	12 mA	—	4,008	—	4,608	—	5,209	ps
1.5-V LVTTTL	2 mA	—	6,789	—	7,807	—	8,825	ps
	4 mA	—	5,109	—	5,875	—	6,641	ps
	8 mA	—	4,793	—	5,511	—	6,230	ps
3.3-V PCI		—	923	—	1,061	—	1,199	ps

Figure 5–1. Cyclone Device Packaging Ordering Information



## Referenced Documents

This chapter references the following documents:

- *Package Information for Cyclone Devices* chapter in the *Cyclone Device Handbook*
- *Quartus II Handbook*

## Document Revision History

Table 5–1 shows the revision history for this chapter.

Table 5–1. Document Revision History		
Date and Document Version	Changes Made	Summary of Changes
May 2008 v1.4	Minor textual and style changes. Added “Referenced Documents” section.	—
January 2007 v1.3	Added document revision history.	—
August 2005 v1.2	Minor updates.	—